

ESD5V0D5B

Description

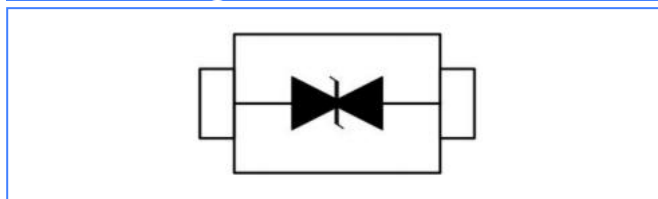
ESD5V0D5B is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium.

Features

- 100 Watts Peak Pulse Power per Line ($t_p=8/20\mu s$)
- Operating voltage: 5V
- Low leakage current
- Package: SOD-523
- Low clamping voltage
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: $\pm 15kV$
 - Contact discharge: $\pm 8kV$
 - IEC61000-4-4 (EFT) 40A (5/50ns)



Functional Diagram



Applications

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Peripherals
- Pagers

Absolute Maximum Ratings($T_{amb}=25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 μs)	P_{PP}	200	Watts
ESD per IEC 61000-4-2 (Air)	V_{ESD}	± 15	KV
ESD per IEC 61000-4-2 (Contact)		± 8	KV
Lead Soldering Temperature	TL	260 (10 sec)	$^{\circ}C$
Operating Temperature Range	T_J	-40 to +125	$^{\circ}C$
Storage Temperature Range	T_{STJ}	-55 to +150	$^{\circ}C$

Electrical Characteristics (TA = 25 °C unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Stand-off Voltage	V_{RWM}				5	V
Reverse Breakdown Voltage	V_{BR}	$I_t = 1mA$	5.6		7.8	V
Reverse Leakage Current	I_R	$V_R = V_{RWM}$			1	μA
Clamping Voltage	V_C	$I_{PP}=5A, t_P = 8/20\mu s$			11.6	V
		$I_{PP}=MAX, t_P = 8/20\mu s$			18.6	V
Junction Capacitance	C_J	$V_R=0V, f = 1MHz$			25	pF

Characteristics Curves

Figure 1- Power Derating Curve

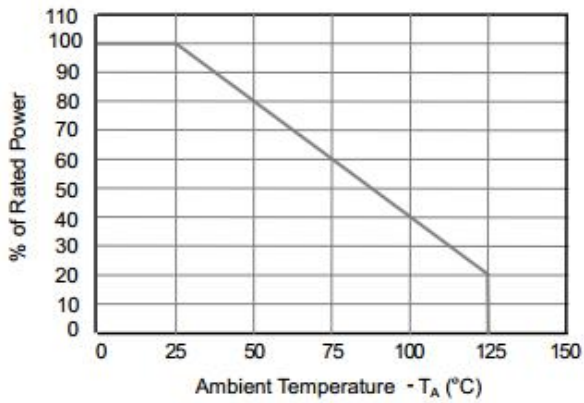


Figure 2- ESD Pulse Waveform (according to IEC 61000-4-2)

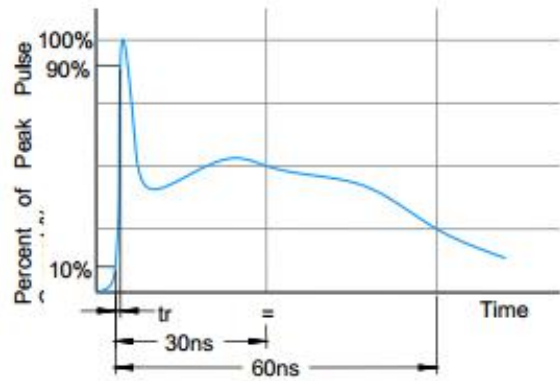
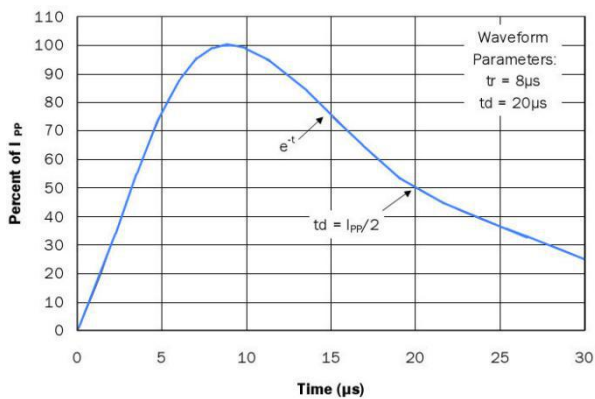
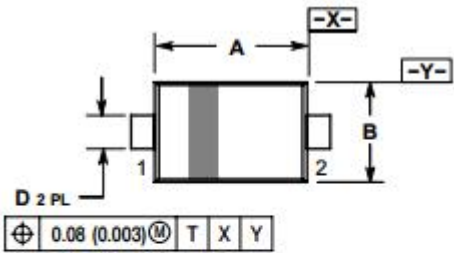


Figure3- 8/20 μs Pulse Waveform

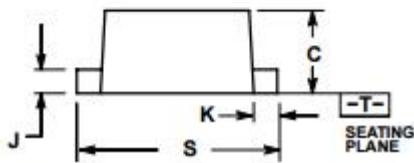


PACKAGE OUTLINE DIMENSIONS in millimeters (inches) :SOD523

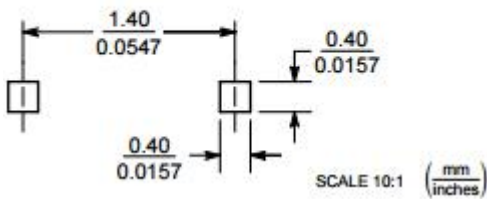


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.10	1.20	1.30	0.043	0.047	0.051
B	0.70	0.80	0.90	0.028	0.032	0.035
C	0.50	0.60	0.70	0.020	0.024	0.028
D	0.25	0.30	0.35	0.010	0.012	0.014
J	0.07	0.14	0.20	0.0028	0.0055	0.0079
K	0.15	0.20	0.25	0.006	0.008	0.010
S	1.50	1.60	1.70	0.059	0.063	0.067



SOLDERING FOOTPRINT*



Disclaimer

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.